

WHAT IS CLAIMED IS:

1. An electroluminescent display device comprising:
a device substrate provided with an electroluminescent element;
5 a sealing substrate attached to the device substrate;
a desiccant layer disposed on the sealing substrate; and
a stress buffering layer disposed between the sealing substrate and the desiccant
layer and configured to relieve stresses generated between the sealing substrate and the
desiccant layer.
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2. The electroluminescent display device of claim 1, wherein the coefficient of
thermal expansion of the stress buffering layer is higher than the coefficient of thermal
expansion of the sealing substrate and lower than the coefficient of thermal expansion of
the desiccant layer.
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3. The electroluminescent display device of claim 1, wherein the stress buffering
layer comprises a layer made of aluminum.
4. The electroluminescent display device of claim 1, wherein the stress buffering
20 layer comprises a layer made of Alq3.
5. The electroluminescent display device of claim 1, wherein the stress buffering
layer comprises a layer made of polyimide.
- 25 6. The electroluminescent display device of claim 1, wherein the stress buffering
layer comprises a layer made of aluminum and a layer made of Alq3.
7. The electroluminescent display device of claim 1, wherein the stress buffering
layer comprises a layer made of aluminum and a layer made of polyimide.
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8. The electroluminescent display device of claim 1, wherein the stress buffering layer comprises a layer made of Alq3 and a layer made of aluminum.

5 9. The electroluminescent display device of claim 1, wherein the device substrate is made of an inorganic glass, a polymeric glass or a composite thereof.

10. The electroluminescent display device of claim 1, wherein the sealing substrate is made of an inorganic glass, a polymeric glass or a composite thereof.

10 11. An electroluminescent display device comprising:
a device substrate provided with an electroluminescent element;
a sealing substrate attached to the device substrate;
a pocket portion formed on a surface of the sealing substrate;
a desiccant layer disposed in the pocket portion; and
15 a stress buffering layer disposed between the sealing substrate and the desiccant layer and configured to relieve stresses generated between the sealing substrate and the desiccant layer.

20 12. The electroluminescent display device of claim 11, wherein the coefficient of thermal expansion of the stress buffering layer is higher than the coefficient of thermal expansion of the sealing substrate and lower than the coefficient of thermal expansion of the desiccant layer.

25 13. The electroluminescent display device of claim 11, wherein the stress buffering layer comprises a layer made of aluminum.

14. The electroluminescent display device of claim 11, wherein the stress buffering layer comprises a layer made of Alq3.

30 15. The electroluminescent display device of claim 11, wherein the stress

buffering layer comprises a layer made of polyimide.

16. The electroluminescent display device of claim 11, wherein the stress buffering layer comprises a layer made of aluminum and a layer made of Alq3.

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17. The electroluminescent display device of claim 11, wherein the stress buffering layer comprises a layer made of aluminum and a layer made of polyimide.

18. The electroluminescent display device of claim 11, wherein the stress buffering layer comprises a layer made of Alq3 and a layer made of aluminum.

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19. The electroluminescent display device of claim 11, wherein the device substrate is made of an inorganic glass, a polymeric glass or a composite thereof.

20. The electroluminescent display device of claim 11, wherein the sealing substrate is made of an inorganic glass, a polymeric glass or a composite thereof.

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21. An electroluminescent display device comprising:
a device substrate provided with an electroluminescent element;
a sealing substrate attached to the device substrate; and
a desiccant containing layer disposed on the sealing substrate and containing a desiccant,

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wherein the coefficient of thermal expansion of the sealing substrate is 10×10^{-6} or less, and the coefficient of thermal expansion of the desiccant containing layer is between 30×10^{-6} and 40×10^{-6} .

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